

REMARKS

Reconsideration of the above-identified application in view of the present amendment and the following remarks is respectfully requested.

Claims 1, 5, 6 and 8 have been amended. Claim 12 has been added.

Claim 1 has been amended to clarify the encapsulation of the base plate 10 and with respect to the cantilevered attachment section 10a. The housing body 36 is formed on the base plate by injection molding with the base plate being surrounded by the injection molded housing body including on the sides and bottom surface of the housing body. On at least one side the base plate projects out of the housing body thus forming a cantilevered attachment section 10a which is used to mount the entire device to a positive cell terminal of a lead accumulator.

Claims 1-12 define over the cited prior art patents to Du Bois et al. (US 4,518,982), Collumeau (US 4,510,677), Verma (US 5,872,332), Tsai (US 6,347,958), Flickinger (US 4,924,152), either alone or in combination with each other.

Regarding claim 1, claim 1 recites a housing for which no attachment means are required to connect the housing body to the base plate because the base plate is integrated into and connected with the housing body by injection molding the housing body to the base plate. Thus, no screw or bolt connection is needed between the housing body and the base plate. In addition, the housing body surrounds the base plate

including around the side surface of the base plate and the bottom surface.

Regarding the patent to Du Bois et al., as can be seen in Fig. 2, the structure includes a base plate 21 and housing body 34. The housing body does not surround the base plate because it lies on top of the base plate and does not extend over the sides and bottom of the base plate. In addition, the housing body is connected to the base plate via bolts or screws through holes at reference number 33.

Regarding the patent to Collumeau, as can be seen in Fig. 3, the structure of the case includes a base plate 1 with a block of sealing substance 30 (epoxy resin) provided on the base plate. The sealing substance does not surround the base plate because it does not extend over the sides of the base plate and over the bottom of the base plate. The epoxy is only applied on one side of the base plate.

A combination of the patents to Du Bois et al. and Collumeau does not lead to the claimed subject matter of an injection molded generally parallelepipedal housing body formed on and surrounding the base plate including on a side and bottom surface of the base plate.

Claim 1 was rejected under 35 USC §103(a). A rejection under 35 USC 103(a) meet three criteria, one of which is that the combination of references used must teach or suggest all of the claimed limitations (MPEP §706.02(j)). Since the cited combination lacks the limitation of an injection molded generally parallelepipedal housing body formed on and surrounding the base plate including on a side and bottom

surface of the base plate, claim 1 is not obvious over the cited combination. Claim 1 should be allowed.

Claims 2-11 depend from claim 1 and are patentable over the cited prior art for the same reasons as claim 1 and for the specific claim limitations recited therein.

Regarding claim 5, none of the prior art, either alone or in combination disclose or suggest that at least one soldering pin is stamped out from the base plate, the soldering pin is perpendicularly bent upwards inside the housing body. Comparing with the patent to Du Bois et al., the terminals 29, 30 are not stamped out from the base plate 21. The terminals are rather fixed on ceramic insulator 22 as is apparent from Fig. 2.

Regarding claim 6, none of the prior art, either alone or in combination disclose or suggest that at least one soldering pin is stamped out from the contact plate, the soldering pin is perpendicularly bent upwards inside the housing body. Comparing with the patent to Du Bois et al., the terminals are not stamped out from the contact plate as the terminals are fixed on ceramic insulator 22 as recited infra.

Regarding claim 8, none of the prior art, either alone or in combination, disclose or suggest that the housing body has an open side opposite the base plate and a removable cover, the cover fitting on the open side of the housing body and being connected to the housing body by an interaction of lock-in openings and corresponding support projections. The patent to Tsai does not disclose this limitation.

Regarding claim 11, none of the cited prior art combination discloses or suggest that the base plate has a contact tag that is bent upwards and that forms a contact surface for a temperature sensor element mounted on a printed circuit board. The patent to Du Bois et al. does not disclose a contact tag forming a surface for a temperature sensor element. The configuration of the contact tag is not an obvious design choice. The surface of the contact tag has a definite function which is not apparent from any of the cited references.

Thus, claims 2-11 should be allowed as well since these claims also define over the cited prior art combinations.

Regarding claim 12, antecedent basis is found in claim 5 and in the specification middle paragraph on page 4. Claim 12 is directed to the entire structure including the housing and a printed circuit board into which the soldering pin 26 of the base plate penetrates. The cited prior art combination does not disclose all of the claim limitations in claim 12. Thus, claim 12 should be allowed.

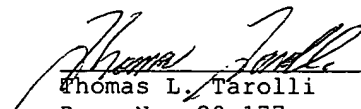
Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

In view of the foregoing, it is respectfully submitted that the above identified application is in condition for allowance, and allowance of the above-identified application is respectfully requested.

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Please charge any deficiency or credit any overpayment in  
the fees for this amendment to our Deposit Account  
No. 20-0090.

Respectfully submitted,

  
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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The following claims have been amended:

1. (Amended) A housing for an electronic monitoring device on a vehicle part such as a lead accumulator, said housing comprising:

- a) a metallic load-bearing base plate;
- b) an injection molded generally parallelepipedal housing body formed on and surrounding said ~~encapsulating the~~ base plate including on a side and bottom surface of the base plate;

said base plate projecting out of said housing body on at least one side, thus forming with a cantilevered attachment section.

5. (Amended) The housing according to claim 1, wherein at least one soldering pin is stamped out from said base plate, said soldering pin being perpendicularly bent upwards inside said housing body ~~said base plate has at least one stamped out soldering pin that is perpendicularly bent upwards inside said housing body.~~

6. (Amended) The housing according to claims 3, wherein at least one soldering pin is stamped out from said contact plate, said soldering pin being perpendicularly bent upwards inside said housing body ~~said contact plate has at least one~~

~~stamped out soldering pin that is perpendicularly bent upwards  
inside said housing body.~~

8. (Amended) The housing according to claim 1, wherein  
said housing body has an open side opposite said base plate  
and a removable cover, said cover fitting fits on the open  
side of said housing body and being connected to said housing  
body by an interaction of lock-in openings and corresponding  
support projections.